WONIK IPS

Company Introduction

We design the dream of leading the digital powerhouse Korea,
the future of the Korean equipment industry.

Securing equipment proprietary technology
through endless R&D, and
taking a bold leap forward to become
the world's best equipment company.
These are Wonik IPS's goals and biggest values.

Contents

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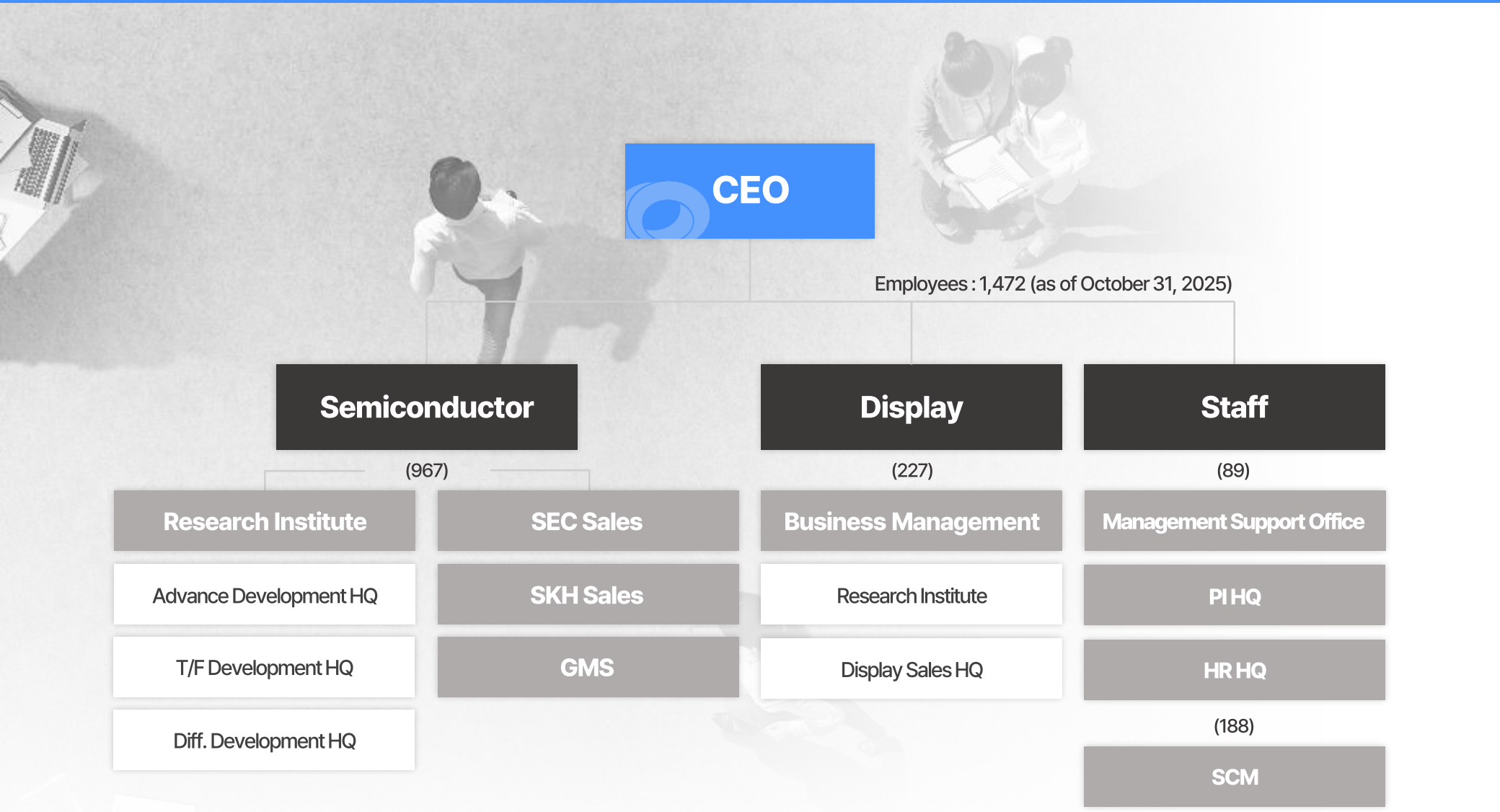
Company Name	WONIK IPS
CEO	Taehyuk Ahn
Established Date	September 19, 1991
Address	75, Jinwisandan-ro, Jinwi-myeon, Pyeongtaek-si, Gyeonggi-do
Employees	1,472 (as of October 31, 2025)
Main Business	Core equipment for front-end processes of semiconductor and display
Capital	24.5 billion won (Total number of issued shares : 49,083,901 shares)
Listed Date	September 24, 1996 (KOSDAQ)
Website	www.ips.co.kr



CEO

Employees : 1,472 (as of October 31, 2025)

Semiconductor (967)

- **Research Institute**
  - Advance Development HQ
  - T/F Development HQ
  - Diff. Development HQ
- **SEC Sales**
- **SKH Sales**
- **GMS**

Display (227)

- **Business Management**
  - Research Institute
  - Display Sales HQ

Staff (89)

- **Management Support Office**
- **PI HQ**
- **HR HQ**

(188)

- **SCM**

At the beginning of localizing semiconductor equipment, you can find WONIK IPS.

We aim to reinvent ourselves as a global equipment maker to better serve the world.

1999~2010

2010.12 ATTO and IPS merged
2006.11 Split off the special gas business division
: WONIK Materials
2005.10 IPS acquired ATTO
1999.01 IPS was incorporated as an affiliate of WONIK

2011~2015

2014.01 13.15% share of Tera Semicon acquired
(listed as the largest shareholder)
2012.06 Dunpo Campus completed
2011.03 Change of company name : WONIK IPS

2016~

2019.02 WONIK IPS and Tera Semicon merged
2016.07 The largest shareholder changed
(from WONIK to WONIK Holdings)
2016.05 Re-listed on KOSDAQ
2016.04 Spun-off the company
: WONIK Holdings, surviving company ;
WONIK IPS, new company

2021~

2022.06 Jinwi 3rd Industrial Complex completed

We contribute to human development

by providing creative technologies and services in a fair and transparent manner

Freedom

Break away from stereotypes or customs, come up with a unique way through open thinking, and take responsibility and perform on our own way

Communication

Ensure that members move toward one direction by understanding each other's position with a sincere heart and sharing each other's experience, knowledge and information based on rational expression

Happiness

Create a pleasant workplace based on trust with all members taking pride in being 'WONIK People', and feel a sense of accomplishment and reward through work

Domestic 5 business sites, 4 CS sites **Overseas** 5 corporations, 1 branch, 1 CS site

Jinwi Campus (HQ)

Semiconductor Clean Room and R&D Lab
- Class 10 Level
- Operation of Parts Development Lab

Semiconductor Sales/STAFF

Giheung Site

Semiconductor Thin film Development
Software /STAFF

Icheon Site

Semiconductor SKH Sales / CS Center

Jinwi 3rd Industrial Complex

Semiconductor Integrated Manufacturing Center
Operation of Training Center
Capacity : T/F 85 System / Month
Diff. 26 System / Month

Dunpo Site

Display Business HQ
Display Manufacturing Center
- Capacity : 80 Chamber / Month

CS Site	Pyeongtaek / Hwaseong / Cheongju / Cheonan	
Overseas	U S	Texas / New York (site)
	China	Xian / Wuxi / Kunshan
	Singapore	Woodland
	Taiwan	Xinzhu (branch)

Our key products include semiconductor, LCD and AMOLED,
and **we are growing as a integrated equipment manufacturer on a global scale**
by diversifying our businesses **through ongoing R&D.**

WONIK IPS Business Portfolio

Semiconductor

Deposition

- GEMIPRO ™ (CVD/ALD)
- NOA ™ (CVD/ALD)
- HyEta ™ (ALD)
- CUARTO VS ™ (CVD)
- LEVATA-CP ™ (CVD)
- CLARO ™ (ALD)
- PRESTO ™ (ALD)
- VELOCE ™ (ALD)

Thermal System

- 300SERIES ™
- MODUS ™

Display

Deposition

- BP PECVD
- TFE PECVD

Etching

- ICP Dry Etcher
- CCP Dry Etcher
- Laser Etcher
- Laser Driller

Thermal System

- PI Cure
- LT/IGZO Furnace

GEMIPRO ™

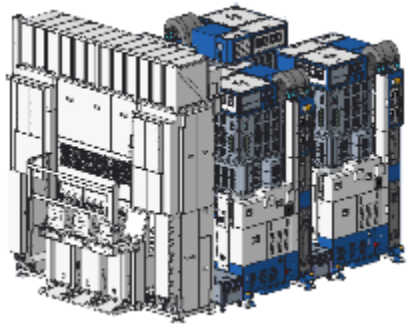
Application process : DRAM / NAND / Logic
Dielectric CVD / ALD
Process : SiON / a-Si / SiO2 (@TEOS,SiH4)
ALD OX / SiN / SiOC / SiCN

Core technologies

1. High Temp. Extreme stability
2. Wafer centering technology
3. Auto level system

CUARTO VS ™

Application process : NAND
Dielectric CVD
Process : ON-Stack, High Thick TEOS,
Seem free Oxide



Core technologies

1. High Throughput, compact layout
2. Minimize dead volume, mini block
3. ESC & IMS
4. Extreme stress control

NOA ™

Application process : DRAM / NAND
Dielectric CVD, ALD
Process : Ti / TiN / W

Core technologies

1. Large capacity, flow rate system
2. Horizontal monitoring system (Stage heater)

HyEta ™

Application process : DRAM / NAND
Dielectric ALD
Process : SIO2 Seamless Gap Fill / ZrO2 / AlO

Core technologies

1. Gas balance control technology
2. Dual pumping structure

300SERIES ™

Application process : DRAM / NAND
Dielectric CVD
Process : Oxidation / Anneal / Alloy / PI bake Poly / ALD Ox/SiN

Core technologies
1. High productivity, small footprint
2. Advanced heater temp. control

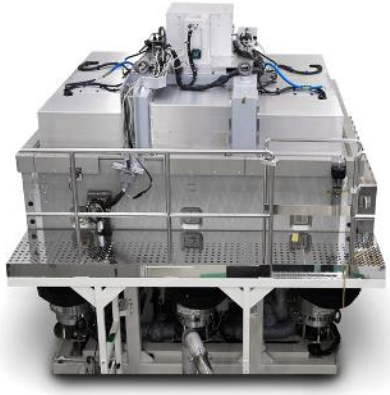
LEVATA-CP ™

Application process : DRAM / NAND
Dielectric CVD
Process : Poly

Core technologies
1. High productivity, small footprint
2. Excellent thickness uniformity
3. Complete load lock control

Dry Etcher

ICP Type Antenna
Process : OLED / a-Si / Oxide

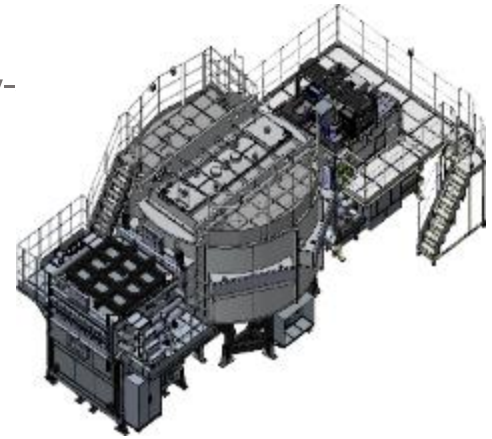


Core technologies

1. High etch rate & throughput
2. Long term PM cycle
3. Easy maintenance

BP PECVD

High Temp. Process
Process : SiNx / SiOx / a-Si / Poly-



Core technologies

1. Low damage plasma mode
2. High quality film uniformity
3. Muti zone & Bias susceptor

Dry Etcher

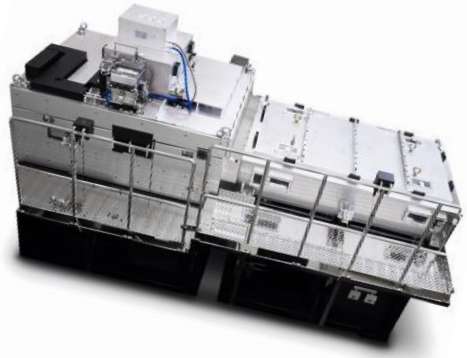
CCP Type
Process : LCD & OLED / a-Si / Oxide

Core technologies

1. High etch rate & throughput
2. Unique arc management
3. Advanced particle management

TFE PECVD

Low Temp. Process
Process : SiON / SiNx / SiO2

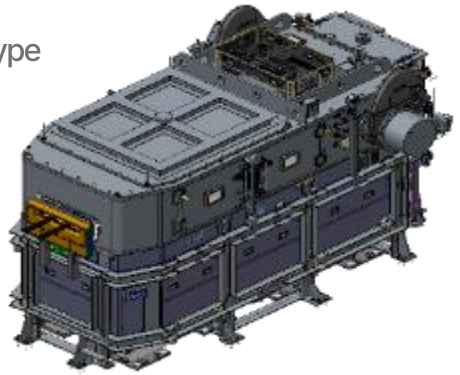


Core technologies

1. Low damage plasma mode
2. High quality film uniformity
3. Controllable film stress

Laser Etcher

Bottom-Up / Top-Down process type
Process : EV In-line etch by laser



Core technologies
1. High precision hole etch
2. High precision moving stage
3. High vacuum process

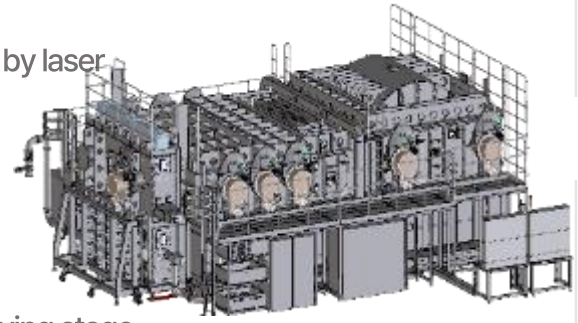
PI Cure

Flexible OLED TFT Backplane
Process : PI Film Cure

Core technologies
1. Fast ramping process
2. Uniform laminar flow control
3. Structure for particle suppression

Laser Driller

Bottom-Up process type
Process : EV In-line drilling by laser



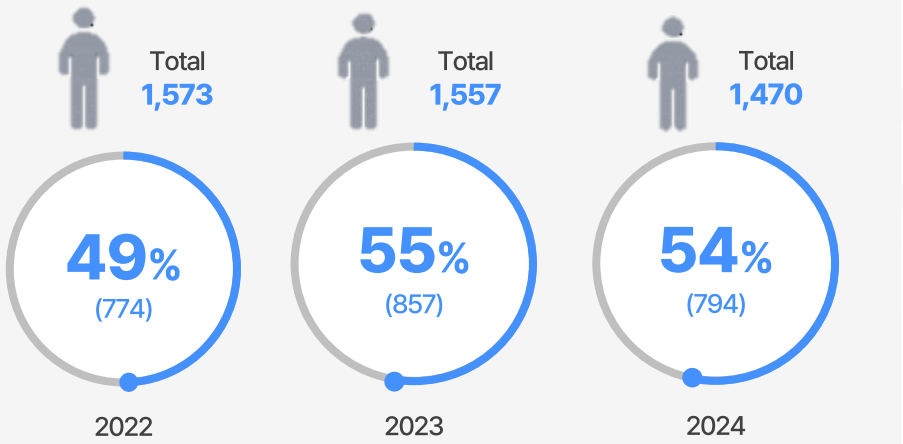
Core technologies
1. High precision Drilling
2. Flip & High precision moving stage
3. High vacuum process

LT Furnace

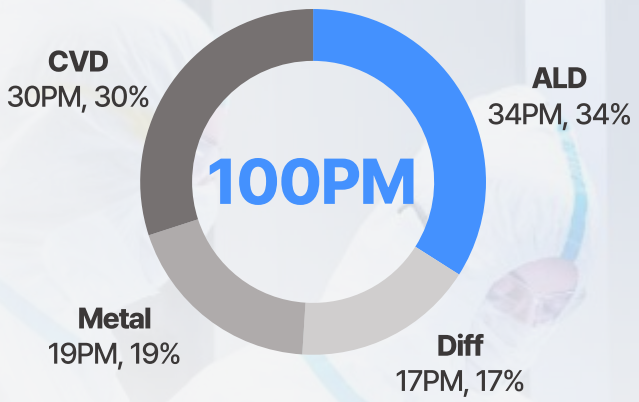
Rigid & Flexible Backplane
Process : Contact Anneal, Activation

Core technologies
1. Excellent temp. uniformity
2. High productivity (Fast ramp up/down)
3. Perfect sealing for O2 density control

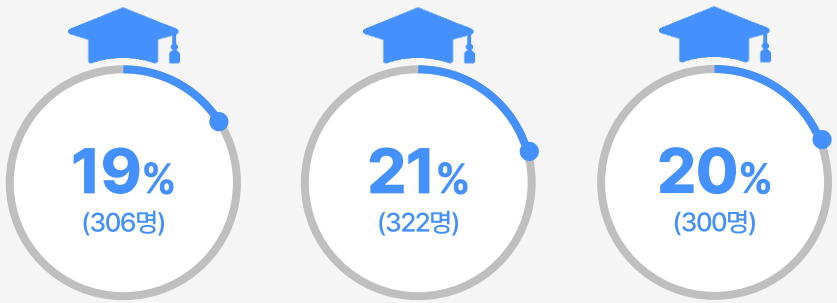
Human Resource
: Status of R&D Manpower



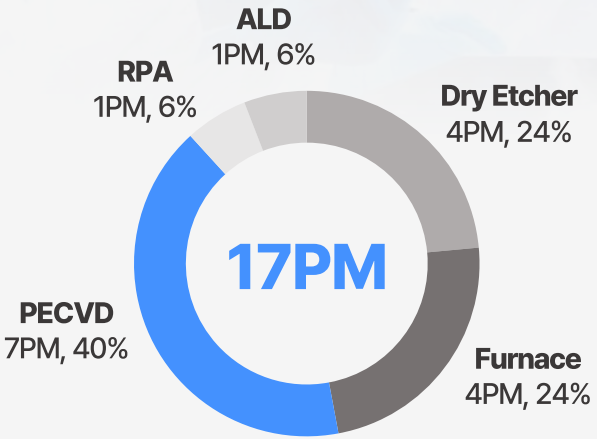
R&D equipment status
: Semiconductor (43PM on 2nd floor, 51PM on 3rd floor, 6PM R&D 2nd Fab)



Human Resource
: Status of Manpower with Master's Degree and Doctoral Degree



R&D facility status
: Display (Jinwi 11PM, Dunpo 4PM, SDC 2PM)



* as of December 31, 2024

Patent application status (including utility model)

Korea 1395 cases, **79%**
China 133 cases, **8%**
Taiwan 100 cases, **6%**
US 66 cases, **4%**
Japan 57 cases, **3%**

(Unit : Number of cases)

	Korea	China	Taiwan	US	Japan	Total
Application	760	64	33	30	12	899
Registration	635	69	67	36	45	852
Total	1,395	133	100	66	57	1,751

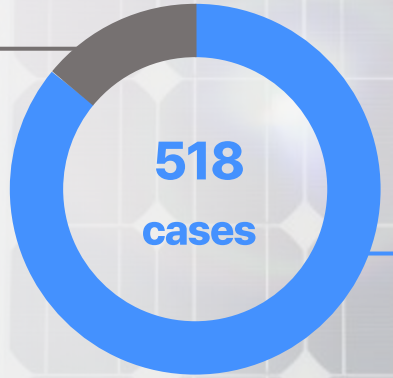
* as of December 31, 2024

Patent application status by business field

Semiconductor (Total 1,233 cases)

Overseas 273 cases, **22%**
Domestic 960 cases, **78%**

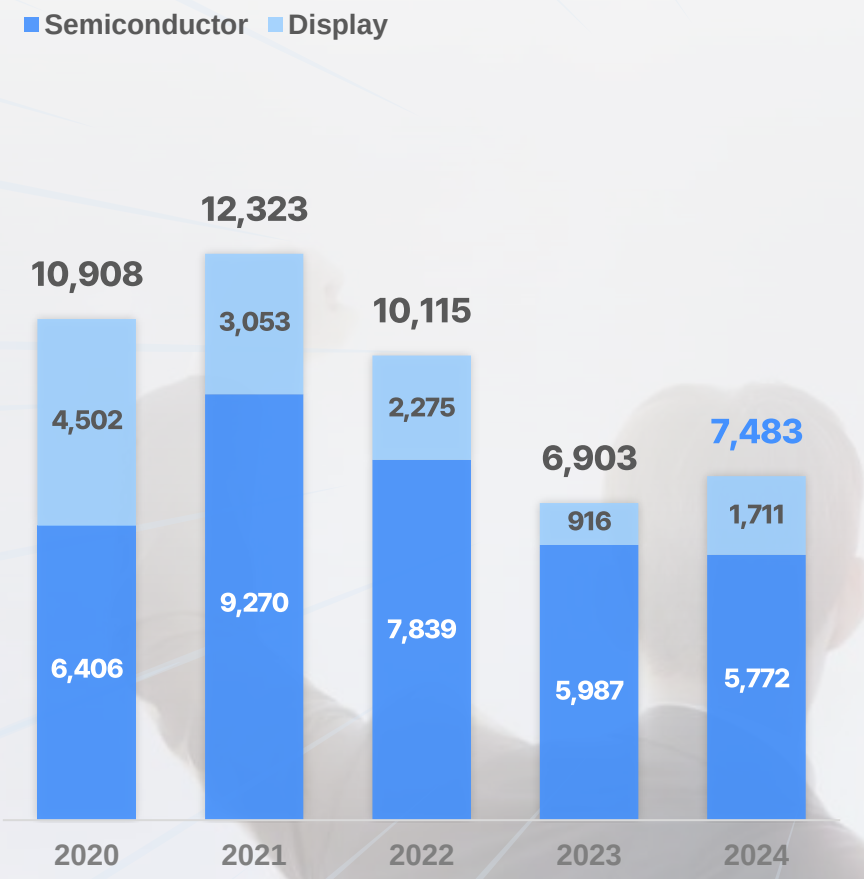
Display (Total 518 cases)



Overseas 83 cases, **16%**
Domestic 435 cases, **84%**

5-year Sales Trend

(Unit: 100 million KRW)



5-year Financial Position

(Unit: 100 million KRW)

	2020	2021	2022	2023	2024
Total Assets	**11,006**	**11,655**	**11,202**	**10,831**	**11,228**
Current Assets	6,561	6,735	5,936	5,840	6,407
Non-Current Assets	4,445	4,920	5,267	4,992	4,821
Total Liabilities	**4,378**	**3,683**	**2,533**	**2,190**	**2,378**
Current Liabilities	4,311	3,611	2,503	2,104	2,302
Non-Current Liabilities	68	71	30	86	76
Total Equity	**6,628**	**7,972**	**8,669**	**8,641**	**8,850**
Capital Stock	245	245	245	245	245
Current Ratio	152%	187%	237%	278%	278%
Liabilities to -Equity Ratio	66%	46%	29%	25%	27%
Debt to Equity Ratio	-	-	-	-	-

* Separate financial statements

ESG

Environment

Create eco-friendly corporate culture through achieving the high level of environmental safety systems

- Establish and monitor hazardous chemical management processes
- Response actively to climate change through energy consumption and greenhouse gas emission management
- Conduct education, inspection and emergency response training
- Reinforce the safety inspections and measurements of working environment to prevent any environmental safety accidents

Social

Ethical management practice through the declaration of compliance management and social contribution activities

- Implement human rights strengthening activities such as humanitarian treatment and prohibition of discrimination
- Selected as 'Best Jobs Company' for 3 consecutive years by contributing to the creation of youth employment and new jobs
- Realize a good company to work for through establishing flexible organizational culture and welfare policy

Governance

Transparent / fair business operation

- Operation of independent and transparent board and audit committee
- Information disclosure and IR activities for shareholders and investors
- Operation of the reporting site, distribution of business guidelines for business partners, etc.

Shared Growth

Reinforcement of innovation capacity

- Performance of consulting and operating training / support programs to strengthen partner company's quality capabilities
- Conducting mutual technology innovation activities through quality exchange meetings

Shared growth index evaluation

- Participation in the shared growth comprehensive evaluation of the Korean Commissions for corporate partnership
- Implementation evaluation of the Fair Trade Agreement by the Fair Trade Commission

Open communication

- Rewarding excellent partners and holding regular exchange meetings
- Operation of the Autonomous Council of Major Partners (Wonwu Association)
- Opening of subcontract VOC windows

Win-win cooperation

- Pursuing shared growth through free equipment rental, technical support, and joint development
- Paying twice a month and operating win-win payment system

Major Affiliates

Semiconductor	Secondary Battery	Trade	Others
WONIK HOLDINGS WONIK IPS WONIK MATERIALS WONIK QnC MOMENTIVE	WONIK PNE PNE POWER & ENERGY SYSTEMS Tech Land	WONIK WONIK CUBE	CMS LAB WONIK L&D WONIK ROBOTICS CARELABS

Sales Trend

(Unit: 100 million KRW)